

CONFIGURABLE MULTIPLE-FUNCTION GATE
Description

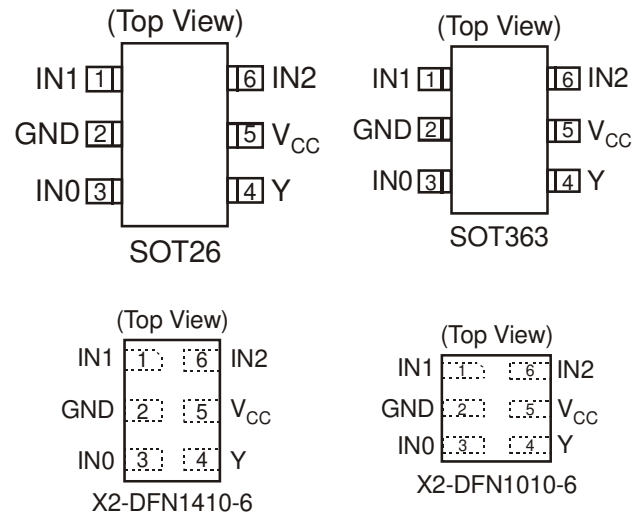
The DIODES™ 74LVC1G97 is a single three-input positive configurable multiple function gate with a standard push-pull output. The output state is determined by eight patterns of three-bit input. The user can choose the logic functions MUX, AND, OR, NAND, NOR, inverter or non-inverting buffer. All inputs can be connected to ground or Vcc as required. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using IOFF. The IOFF circuitry disables the output preventing damaging current backflow when the device is powered down. The user is reminded that the device can simulate several types of logic gates but may respond differently due to the Schmitt action at the inputs.

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- ± 24mA Output Drive at 3.3V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115-A)
 - 2000-V Human Body Model (A114-A)
- Latch-Up Exceeds 100mA per JESD 78, Class II
- Range of Package Options
- SOT26, SOT363, X2-DFN1410-6, and X2-DFN1010-6: Available in "Green" Molding Compound (no Br, Sb)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

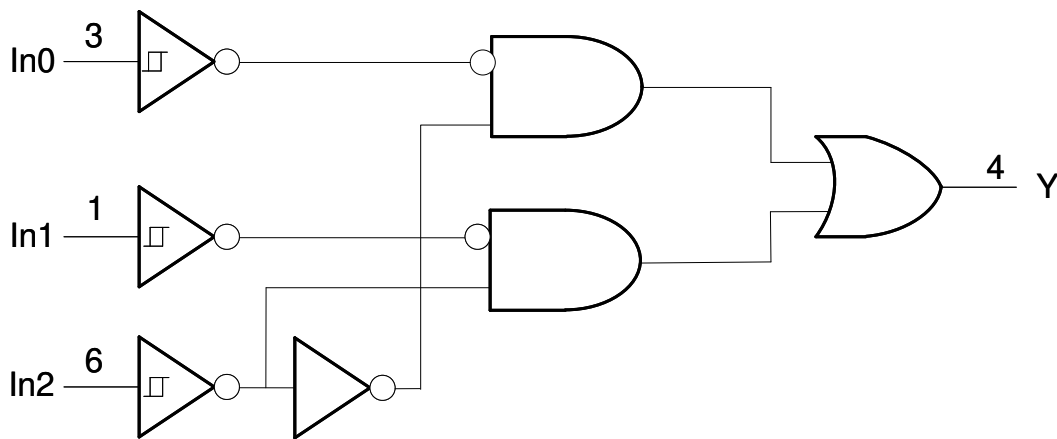
Pin Assignments

Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products such as:
 - PCs, networking, notebooks, netbooks, PDAs
 - Computer peripherals, hard drives, CD/DVD ROM
 - TV, DVD, DVR, set top box
 - Cell Phones, Personal Navigation / GPS
 - MP3 players, Cameras, Video Recorders

Pin Descriptions

Pin Name	Description
IN1	Data Input
GND	Ground
IN0	Data Input
Y	Data Output
V _{CC}	Supply Voltage
IN2	Data Input

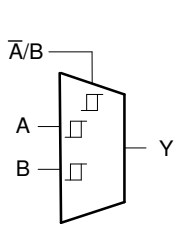
Logic Diagram



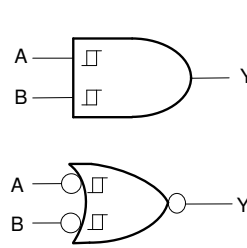
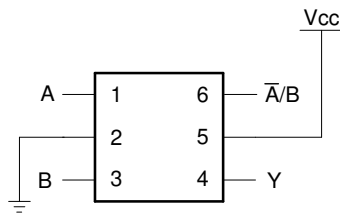
Function Table

Inputs			Output
IN2	IN1	IN0	Y
L	L	L	L
L	L	H	L
L	H	L	H
L	H	H	H
H	L	L	L
H	L	H	H
H	H	L	L
H	H	H	H

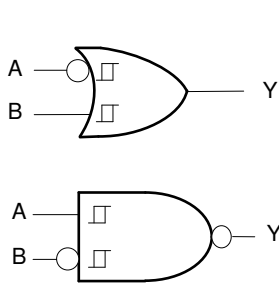
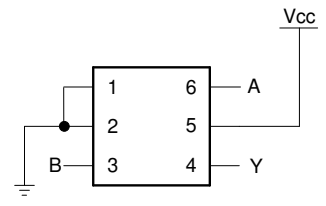
Logic Configurations



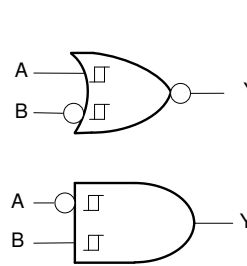
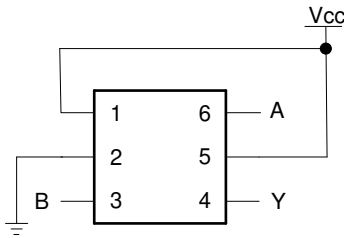
Configuration 1
2 to 1 Data Selector



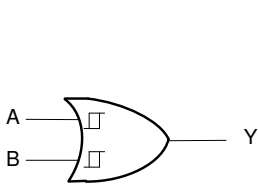
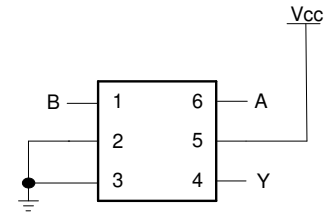
Configuration 2
2-Input AND Gate
2-Input NOR Gate with Both Inputs Inverted



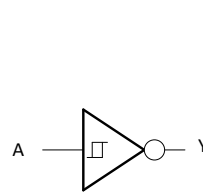
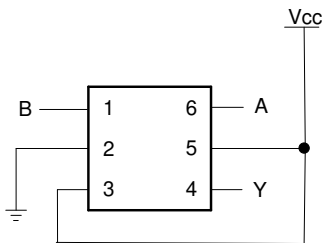
Configuration 3
2-Input NAND Gate with B Input Inverted
2-Input OR Gate with A Input Inverted



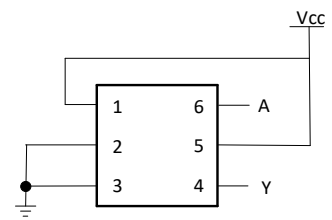
Configuration 4
2-Input NOR Gate with One Input Inverted
2-Input AND Gate with One Input Inverted



Configuration 5
2-Input OR Gate



Configuration 6
Inverter



Function Selection Table	
Logic Function	Configuration
2-to-1 Data Selector	1
2-input AND gate	2
2-input AND with inverted input	3, 4
2-input NOR with inverted input	3, 4
2-input OR	5
2-input NOR with both inputs inverted	2
1-input Inverter	6

Absolute Maximum Ratings (Note 4)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
V _O	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous output current	±50	mA
	Continuous current through V _{DD} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5)

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data retention only	1.5	—	V
V _I	Input Voltage	0	5.5	V	
V _O	Output Voltage	0	V _{CC}	V	
I _{OH}	High-Level Output Current	V _{CC} = 1.65V	—	-4	mA
		V _{CC} = 2.3V	—	-8	
		V _{CC} = 3V	—	-16	
		V _{CC} = 4.5V	—	-24	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 3V	—	16	
		V _{CC} = 4.5V	—	24	
T _A	Operating Free-Air Temperature	—	-40	+125	°C

Note: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = -40°C to +85°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ	Max	Unit
V _{T+}	Positive-going input threshold voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V _{T-}	Negative-going input threshold voltage	—	1.65V	0.30	—	0.72	—
		—	2.3V	0.58	—	1.00	—
		—	3V	0.80	—	1.30	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV _T	Hysteresis (V _{T+} - V _{T-})	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.40	—	0.80	—
		—	3V	0.35	—	1.00	—
		—	4.5V	0.55	—	1.10	—
		—	5.5V	0.60	—	1.20	—
V _{OH}	High Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	—	V
		I _{OH} = -4mA	1.65V	1.2	—	—	
		I _{OH} = -8mA	2.3V	1.9	—	—	
		I _{OH} = -16mA	3V	2.4	—	—	
		I _{OH} = -24mA		2.3	—	—	
		I _{OH} = -32mA	4.5V	3.8	—	—	
V _{OL}	High-level Input Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	—	0.1	V
		I _{OL} = 4mA	1.65V	—	—	0.45	
		I _{OL} = 8mA	2.3V	—	—	0.3	
		I _{OL} = 16mA	3V	—	—	0.4	
		I _{OL} = 24mA		—	—	0.55	
		I _{OL} = 32mA	4.5V	—	—	0.55	
I _I	Input Current	V _I = 5.5V or GND	0 to 5.5V	—	—	± 1	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	—	± 2	μA
I _{CC}	Supply Current	V _I = 5.5V of GND I _O =0	1.65V to 5.5V	—	—	4	μA
ΔI _{CC}	Additional Supply Current	One input at V _{CC} -0.6V Other inputs at V _{CC} or GND	3V to 5.5V	—	—	500	μA

Electrical Characteristics (Continued) (@T_A = -40°C to +85°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ	Max	Unit
V _{T+}	Positive-going input threshold voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V _{T-}	Negative-going input threshold voltage	—	1.65V	0.30	—	0.75	—
		—	2.3V	0.58	—	1.03	—
		—	3V	0.80	—	1.33	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV _T	Hysteresis (V _{T+} - V _{T-})	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.37	—	0.80	—
		—	3V	0.32	—	1.00	—
		—	4.5V	0.50	—	1.20	—
		—	5.5V	0.55	—	1.40	—
V _{OH}	High Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	—	V
		I _{OH} = -4mA	1.65V	0.95	—	—	
		I _{OH} = -8mA	2.3V	1.7	—	—	
		I _{OH} = -16mA	3V	1.9	—	—	
		I _{OH} = -24mA		2.0	—	—	
		I _{OH} = -32mA	4.5V	3.4	—	—	
V _{OL}	High-level Input Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	—	0.1	V
		I _{OL} = 4mA	1.65V	—	—	0.7	
		I _{OL} = 8mA	2.3V	—	—	0.45	
		I _{OL} = 16mA	3V	—	—	0.6	
		I _{OL} = 24mA		—	—	0.8	
		I _{OL} = 32mA	4.5V	—	—	0.8	
I _I	Input Current	V _I = 5.5V or GND	0 to 5.5V	—	—	± 1	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	—	± 2	μA
I _{CC}	Supply Current	V _I = 5.5V of GND I _O = 0	1.65V to 5.5V	—	—	4	μA
ΔI _{CC}	Additional Supply Current	One input at V _{CC} - 0.6V Other inputs at V _{CC} or GND	3V to 5.5V	—	—	500	μA

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
C_i	Input Capacitance	$V_i = V_{CC} - \text{or GND}$	3.3	—	3.5	—	pF
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT26	(Note 6)	—	204	—	$^\circ C/W$
		SOT363		—	371	—	
		X2-DFN1410-6		—	430	—	
		X2-DFN1010-6		—	510	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT26	(Note 6)	—	52	—	$^\circ C/W$
		SOT363		—	143	—	
		X2-DFN1410-6		—	190	—	
		X2-DFN1010-6		—	250	—	

Note: 6. Test condition for SOT26, SOT363, X2-DFN1410-6 and X2-DFN1010-6 : Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^\circ C$ to $+85^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 1)

Parameter	From (Input)	TO (OUTPUT)	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 5V \pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	Any	Y	1.0	14.4	0.7	8.3	0.7	6.3	0.7	5.1	ns

$T_A = -40^\circ C$ to $+125^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 1)

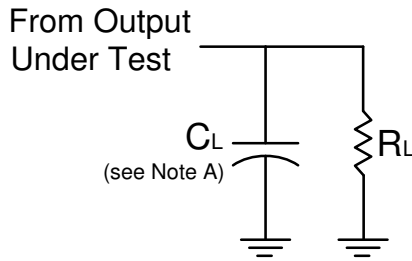
Parameter	From (Input)	TO (OUTPUT)	$V_{CC} = 1.8V \pm 0.15V$		$V_{CC} = 2.5V \pm 0.2V$		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 5V \pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	Any	Y	1.0	18.0	0.7	10.4	0.7	7.9	0.7	6.4	ns

Operating Characteristics

$T_A = +25^\circ C$

Parameter	Test Conditions	$V_{CC} = 1.8V$	$V_{CC} = 2.5V$	$V_{CC} = 3.3V$	$V_{CC} = 5V$	Unit	
		Typ.	Typ.	Typ.	Typ.		
C_{pd}	Power dissipation capacitance	$f = 10 \text{ MHz}$	22	22	23	24	pF

Parameter Measurement Information



V _{CC}	Inputs		V _M	C _L	R _L
	V _I	t _r /t _f			
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1KΩ
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω

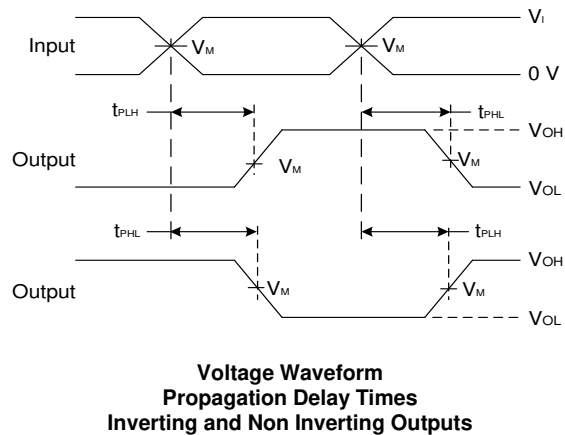
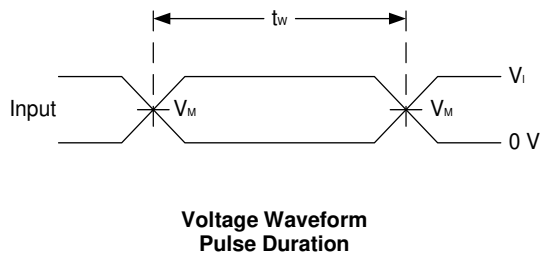
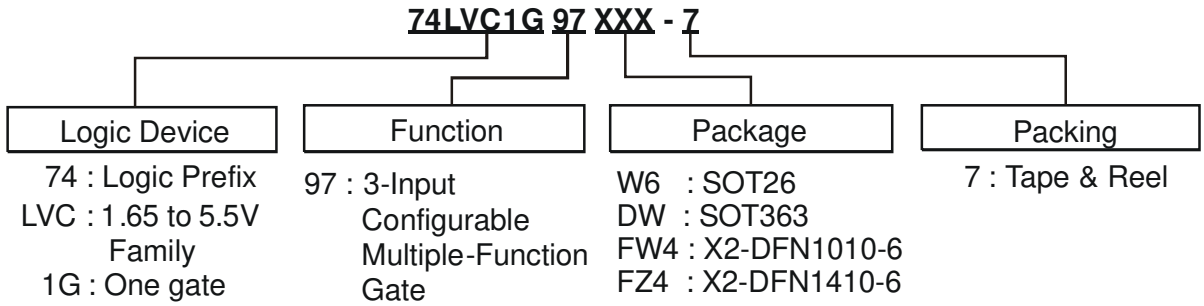


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Ordering Information (Note 7)

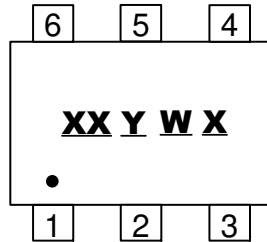


Device	Package Code	Packaging	7" Tape and Reel	
			Quantity	Part Number Suffix
74LVC1G97W6-7	W6	SOT26	3,000/Tape & Reel	-7
74LVC1G97DW-7	DW	SOT363	3,000/Tape & Reel	-7
74LVC1G97FW4-7	FW4	X2-DFN1010-6	5,000/Tape & Reel	-7
74LVC1G97FZ4-7	FZ4	X2-DFN1410-6	5,000/Tape & Reel	-7

Note: 7. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

(1) SOT26, SOT363

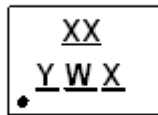


XX : Identification code
Y : Year 0~9
W : Week : A~Z : 1~26 week;
 a~z : 27~52 week; z represents
 52 and 53 week
X : A~Z : Internal Code

Part Number	Package	Identification Code
74LVC1G97W6	SOT26	TY
74LVC1G97DW	SOT363	TY

(2) X2-DFN1010-6, X2-DFN1410-6

(Top View)



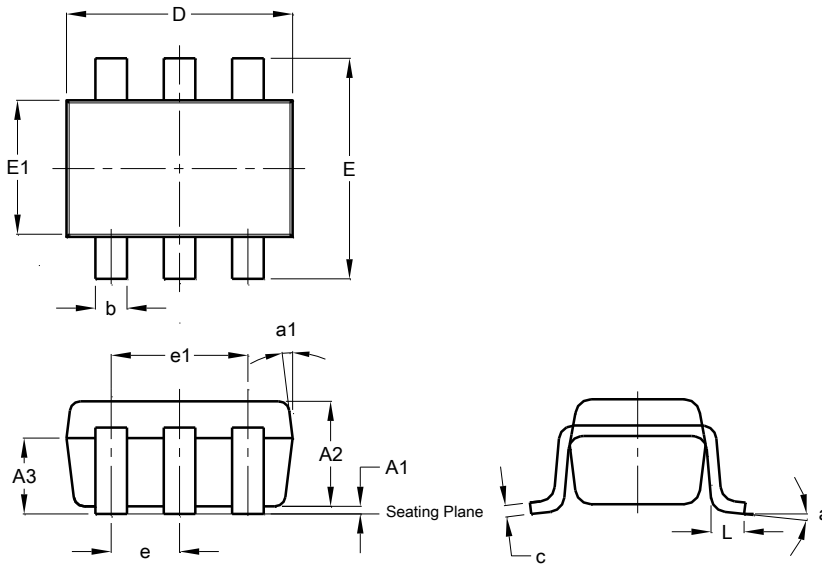
XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
 a~z : 27~52 week; z represents
 52 and 53 week
X : A~Z : Internal code

Part Number	Package	Identification Code
74LVC1G97FW4	X2-DFN1010-6	TY
74LVC1G97FZ4	X2-DFN1410-6	TY

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



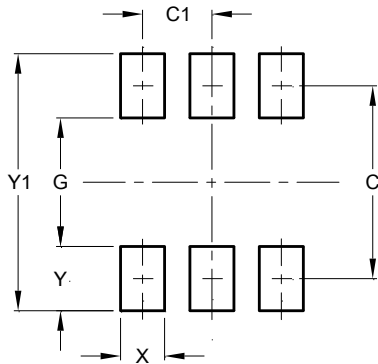
SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



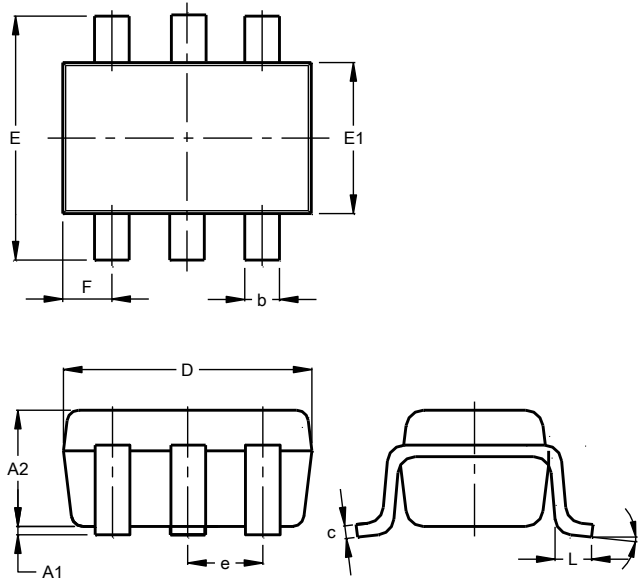
Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363

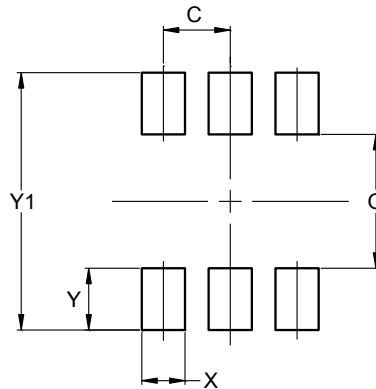


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363



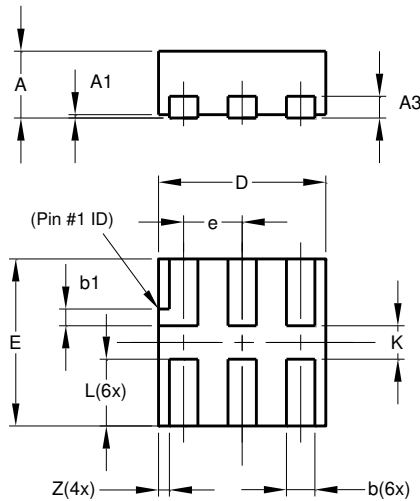
Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6

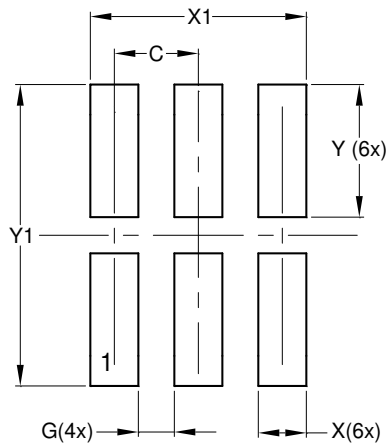


X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6



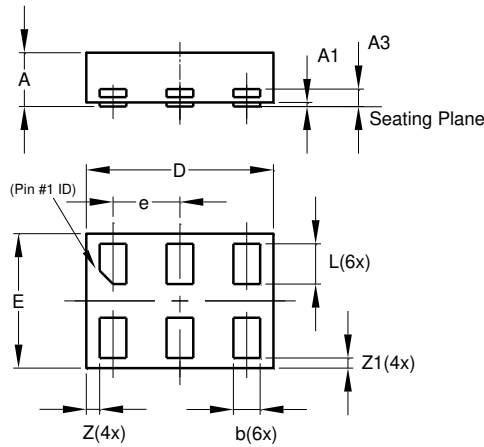
Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6

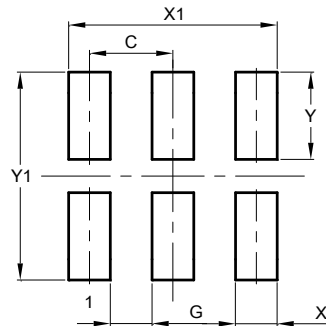


X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

IMPORTANT NOTICE

1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
5. Diodes' products are provided subject to Diodes' Standard Terms and Conditions of Sale (<https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/>) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.
9. This Notice may be periodically updated with the most recent version available at <https://www.diodes.com/about/company/terms-and-conditions/important-notice>

DIODES is a trademark of Diodes Incorporated in the United States and other countries.
The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries.
© 2022 Diodes Incorporated. All Rights Reserved.

www.diodes.com